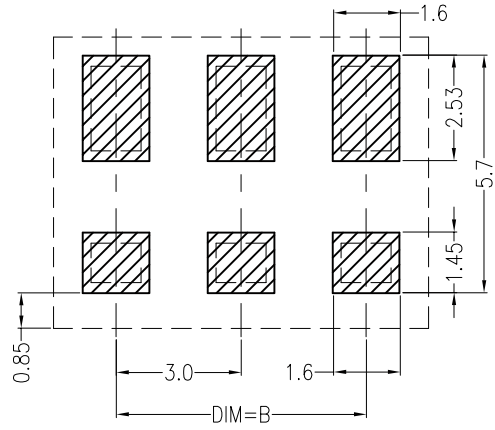
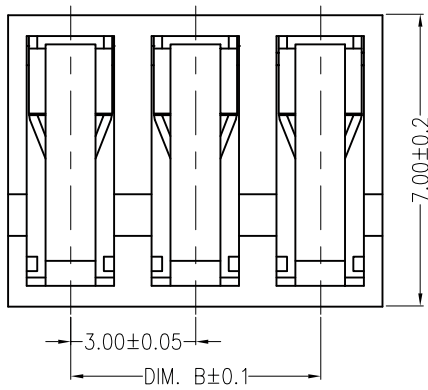
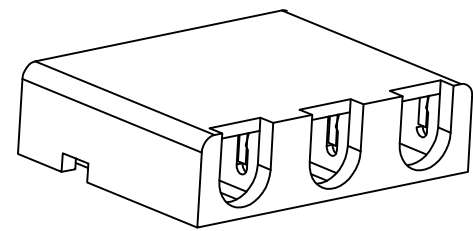
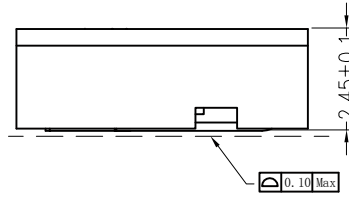
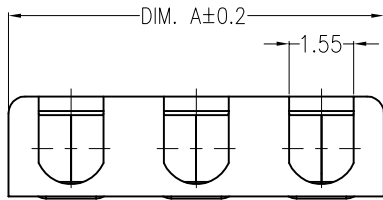


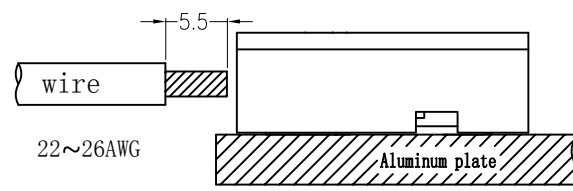
REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



Board Layout

主要技术参数 Main Specifications

- 线数 (Poles): 01 to 03
- 接触电阻 (Contact resistance): $\leq 20m\Omega$
- 绝缘电阻 (Insulation resistance): $\geq 800M\Omega$
- 额定电压 (Rated voltage): 250 V AC DC
- 额定电流 (Rated current): 2.0A AC DC
- 耐电压 (Withstand Voltage): 1500V AC/minute
- 温度范围 (Temperature Range): $-40^{\circ}C \sim +110^{\circ}C$



Assembly Layout

	DIM.A	DIM.B
01	3.00	
02	6.00	3.00
03	9.00	6.00

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C				
B	CONTACT	1~3 PCS	PhosphorBronze	MATTE Sn-plated
A	PEDESTAL	1 PCS	PA9T	UL 94V-0, COLOR:BEIGE

LEDsconn			TITLE: -	
			3.0mmPITCH 180°WAFER SMT TYPE	
X.±0.5	X.±5°	USE: CUSTOMER	PART NO.:	
.X±0.3	.X±2°			
.XX±0.25	.XX±1°	APPD: 邵敬和	DWG NO.:	
--	--	CHKD: 田峰		
UNITS: mm		DR: 蒋建银	SCALE 1 : 1	SHEET 1 / 1